

General Description

SFGMOS[®]

low

$R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics. The low V_{th} series is specially designed to use in synchronous rectification power systems with low driving voltage.

Features

- Low $R_{DS(ON)}$ & FOM
- Extremely low switching loss
- Excellent reliability and uniformity
- Fast switching and soft recovery



Applications

- PD charger
- Motor driver
- Switching voltage regulator
- DC-DC convertor
- Switched mode power supply

Key Performance Parameters

Parameter	Value	Unit
$V_{DS, min} @ T_j(max)$	100	V
$I_D, pulse$	120	A
$R_{DS(ON) max} @ V_{GS}=10V$	20	
Q_g	19.8	nC

Marking Information

Product Name	Package	Marking
SFG10R20AF	TO251	SFG10R20A

Package & Pin information



Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	V_{DS}	100	V
Gate source voltage	V_{GS}	± 20	V
Continuous drain current ¹⁾ , $T_C=25^\circ\text{C}$	I_D	40	A
Pulsed drain current ²⁾ , $T_C=25^\circ\text{C}$	$I_{D,\text{pulse}}$	120	A
Continuous diode forward current ¹⁾ , $T_C=25^\circ\text{C}$	I_S	40	A
Diode pulsed current ²⁾ , $T_C=25^\circ\text{C}$	$I_{S,\text{Pulse}}$	120	A
Power dissipation ³⁾ , $T_C=25^\circ\text{C}$	P_D	72	W
Single pulsed avalanche energy ⁵⁾	E_{AS}	30	mJ
Operation and storage temperature	T_{stg}, T_j	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	R	1.74	$^\circ\text{C}/\text{W}$
Thermal resistance, junction-ambient ⁴⁾	R	62	$^\circ\text{C}/\text{W}$

Electrical Characteristics at $T_j=25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage Gate threshold	BV_{DSS}	100			V	$V_{GS}=0 \text{ V}$, $I_D=250 \text{ A}$

Dynamic Characteristics

Parameter

Electrical Characteristics Diagrams

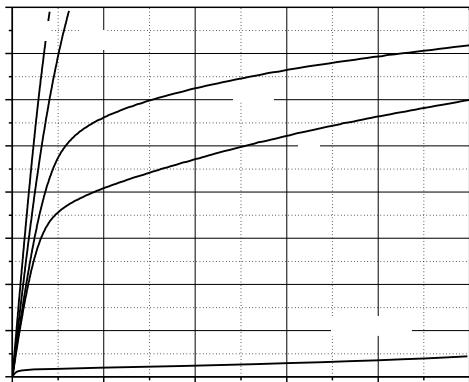


Figure 1. Typ. output characteristics

Figure 2. Typ. transfer characteristics

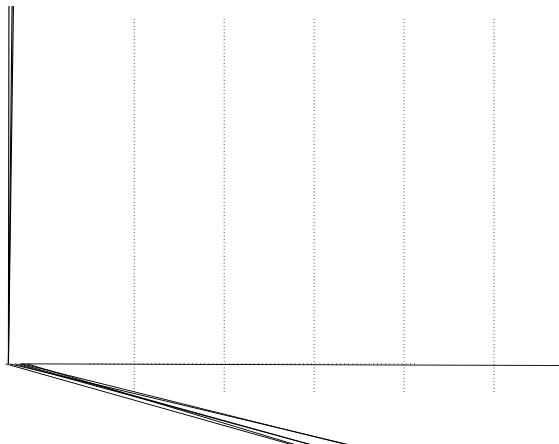


Figure 3. Typ. capacitances



Figure 4. Typ. gate charge

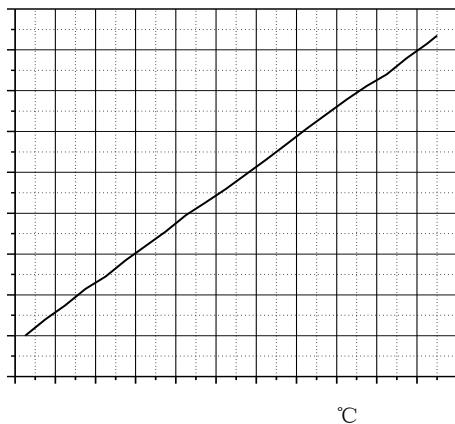


Figure 5. Drain-source breakdown voltage

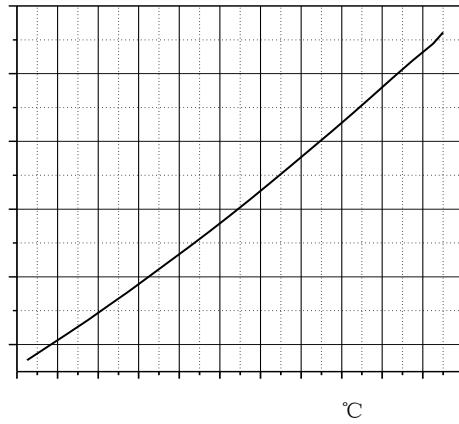


Figure 6. Drain-source on-state resistance

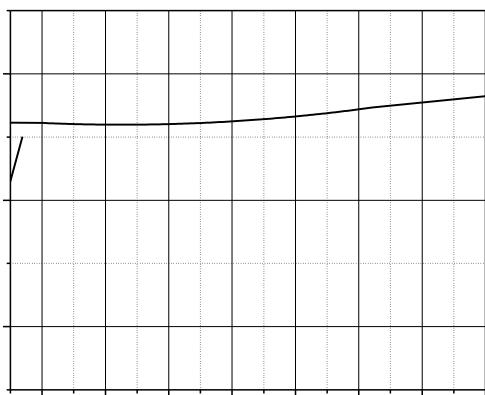


Figure 7. Drain-source on-state resistance

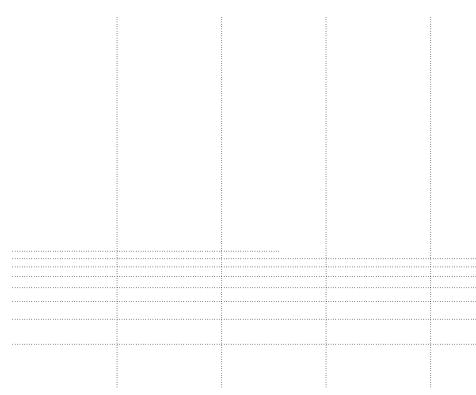


Figure 8. Forward characteristic of body diode



Figure 9. Safe operation area $T_c=25\text{ }^\circ\text{C}$

Test circuits and waveforms

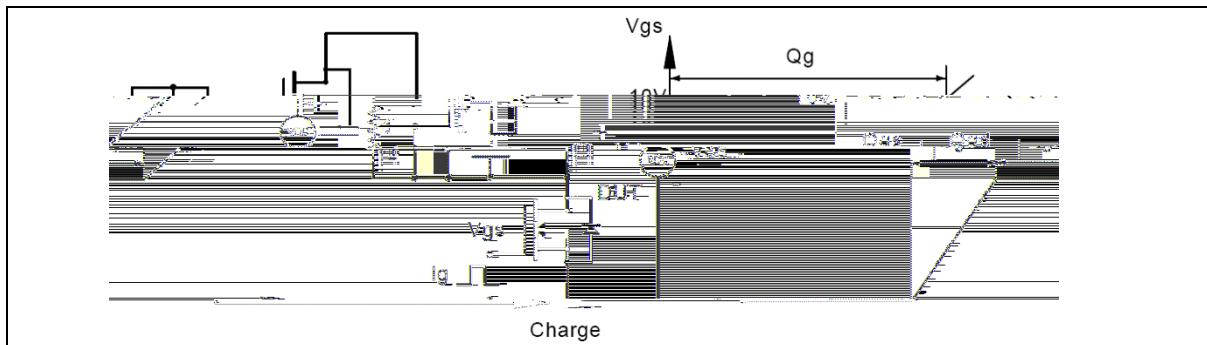


Figure 1. Gate charge test circuit & waveform

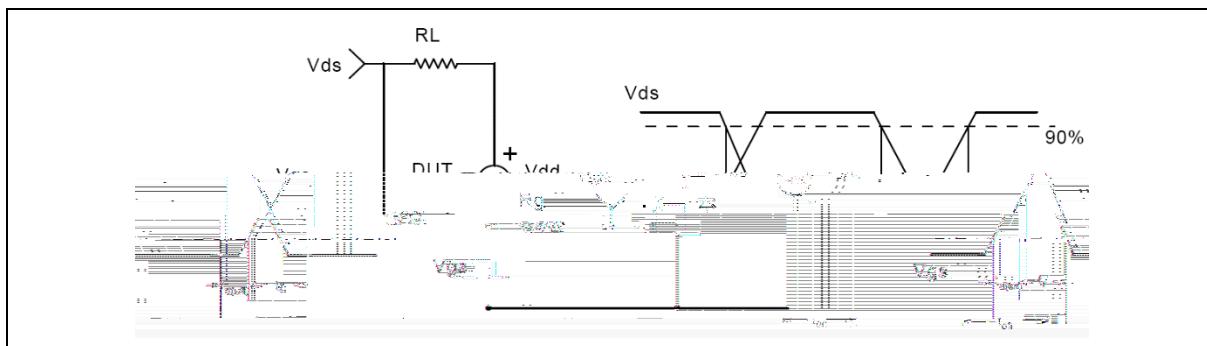


Figure 2. Switching time test circuit & waveform

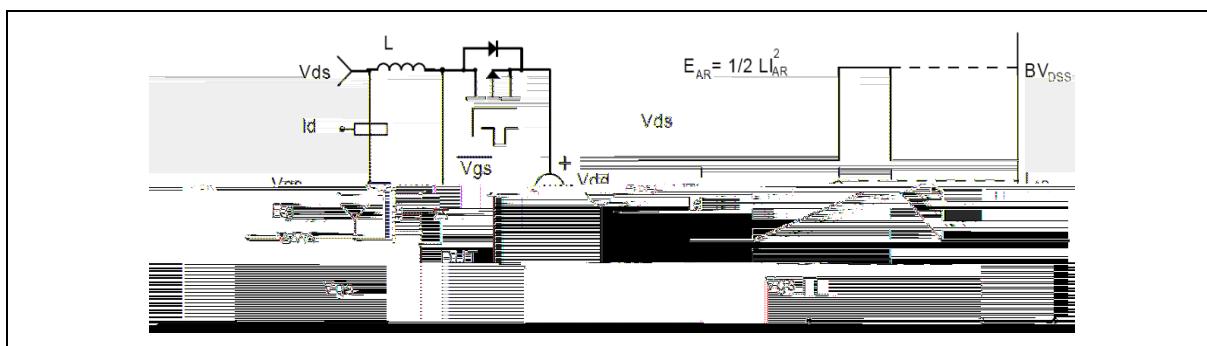


Figure 3. Unclamped inductive switching (UIS) test circuit & waveform

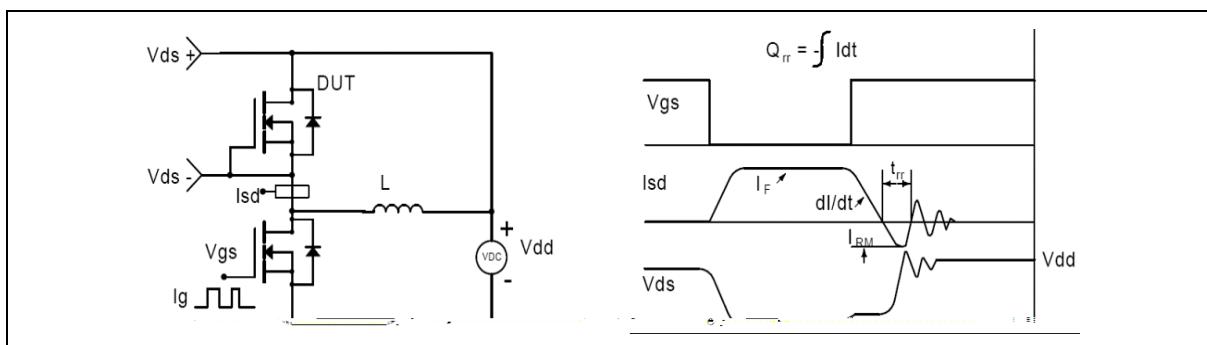
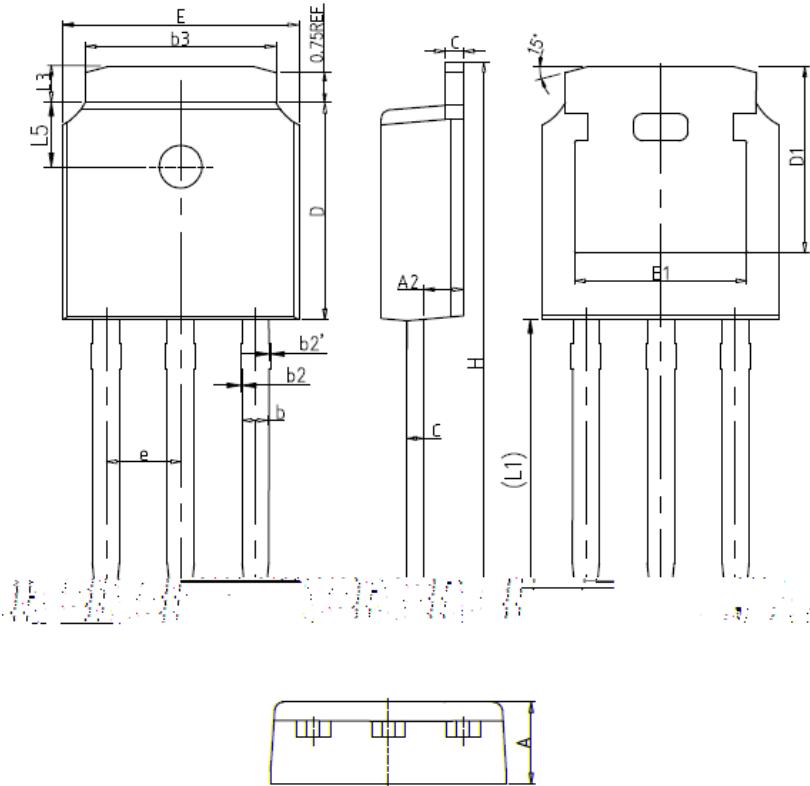


Figure 4. Diode reverse recovery test circuit & waveform

Package Information



Symbol	mm		
	Min	Nom	Max
A	2.20	2.30	2.40
A2	0.97	1.07	1.17
b	0.68	0.78	0.90
b2	0.00	0.04	0.10
	0.00	0.04	0.10
b3	5.20	5.33	5.50
c	0.43	0.53	0.63
D	5.98	6.10	6.22
D1	5.30REF		
E	6.40	6.60	6.80
E1	4.63	-	-
e	2.286BSC		
H	16.22	16.52	16.82
L1	9.15	9.40	9.65
L3	0.88	1.02	1.28
L5	1.65	1.80	1.95

Version 1: TO251-C package outline dimension



Ordering Information

Package Type	Units/Tube	Tubes / Inner Box	Units/ Inner Box	Inner Boxes/ Carton Box	Units/ Carton Box
TO251-C	75	66	4950	6	29700